

N- and P-Channel 12-V (D-S) MOSFET

PRODUCT SUMMARY

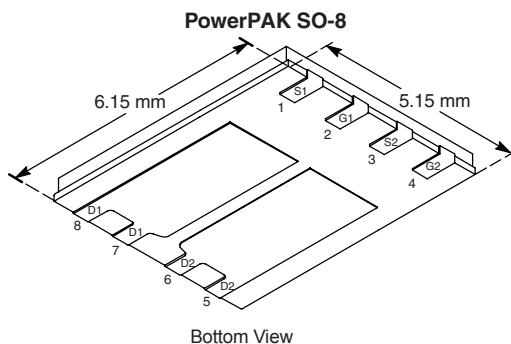
	V_{DS} (V)	$R_{DS(on)}$ (Ω)	I_D (A)
N-Channel	12	0.017 at $V_{GS} = 4.5$ V	11.8
		0.025 at $V_{GS} = 2.5$ V	9.8
P-Channel	- 12	0.032 at $V_{GS} = - 4.5$ V	- 8.9
		0.053 at $V_{GS} = - 2.5$ V	- 6.9

FEATURES

- Halogen-free According to IEC 61249-2-21 Available
- TrenchFET® Power MOSFETs
- New Low Thermal Resistance PowerPAK® Package with Low 1.07 mm Profile
- PWM Optimized for High Efficiency
- 100 % R_g Tested



RoHS
COMPLIANT
HALOGEN
FREE
Available

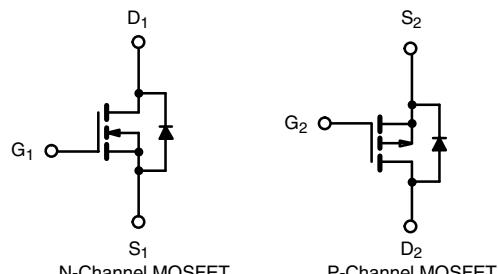


Bottom View

Ordering Information: Si7540DP-T1-E3 (Lead (Pb)-free)
Si7540DP-T1-GE3 (Lead (Pb)-free and Halogen-free)

APPLICATIONS

- Point-of-Load Synchronous Rectifier
 - 5 V or 3.3 V BUS Step Down
 - Q_g Optimized for 500 kHz Operation
- Synchronous Buck, Shoot-Thru Resistant



ABSOLUTE MAXIMUM RATINGS $T_A = 25$ °C, unless otherwise noted

Parameter	Symbol	N-Channel		P-Channel		Unit
		10 s	Steady	10 s	Steady	
Drain-Source Voltage	V_{DS}		12		- 12	V
Gate-Source Voltage	V_{GS}			± 8		
Continuous Drain Current ($T_J = 150$ °C) ^a	I_D	11.8	7.6	- 8.9	- 5.7	A
		9.5	6.1	- 7.1	- 4.6	
Pulsed Drain Current	I_{DM}			20		
Continuous Source Current (Diode Conduction) ^a	I_S	2.9	1.1	- 2.9	- 1.1	
Maximum Power Dissipation ^a	P_D	3.5	1.4	3.5	1.4	W
		2.2	0.9	2.2	0.9	
Operating Junction and Storage Temperature Range	T_J, T_{stg}			- 55 to 150		°C
Soldering Recommendations (Peak Temperature) ^{b,c}				260		

THERMAL RESISTANCE RATINGS

Parameter	Symbol	N-Channel		P-Channel		Unit
		Typical	Maximum	Typical	Maximum	
Maximum Junction-to-Ambient ^a	R_{thJA}	26	35	26	35	°C/W
		60	85	60	85	
Maximum Junction-to-Case (Drain)	Steady State	R_{thJC}	3.9	5.5	3.9	5.5

Notes:

- Surface Mounted on 1" x 1" FR4 board.
- See Solder Profile (www.vishay.com/ppg?73257). The PowerPAK SO-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- Rework Conditions: manual soldering with a soldering iron is not recommended for leadless components.

SPECIFICATIONS $T_J = 25^\circ\text{C}$, unless otherwise noted

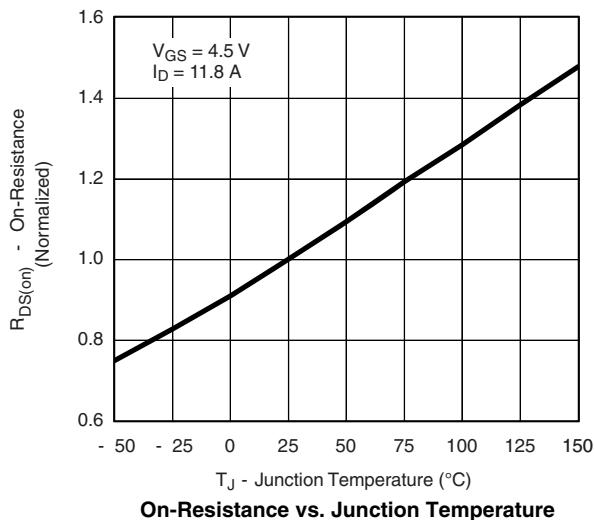
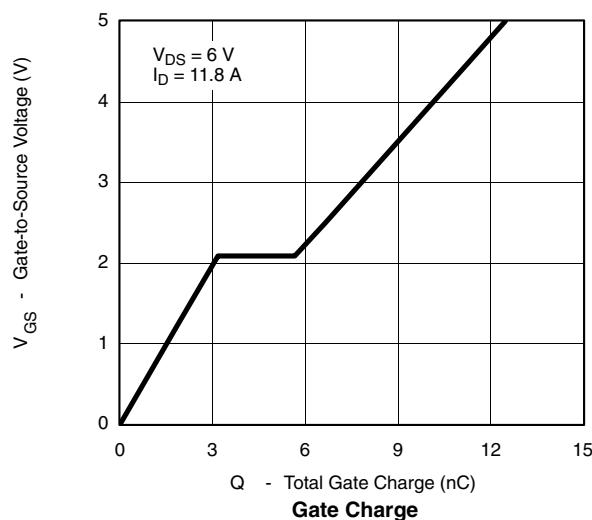
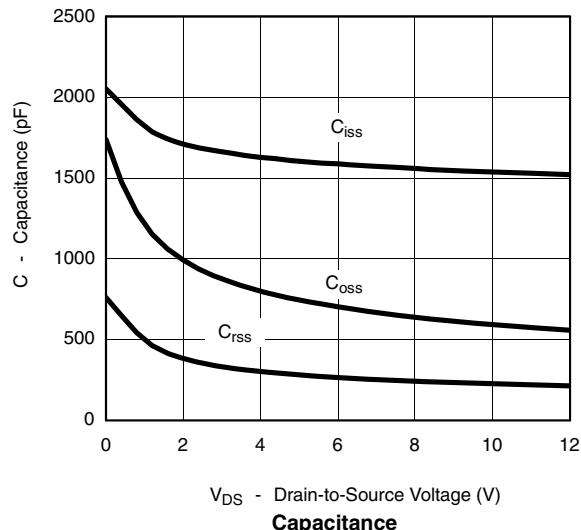
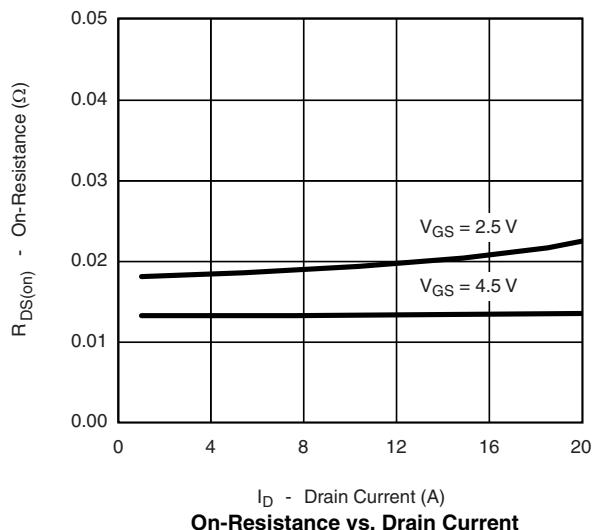
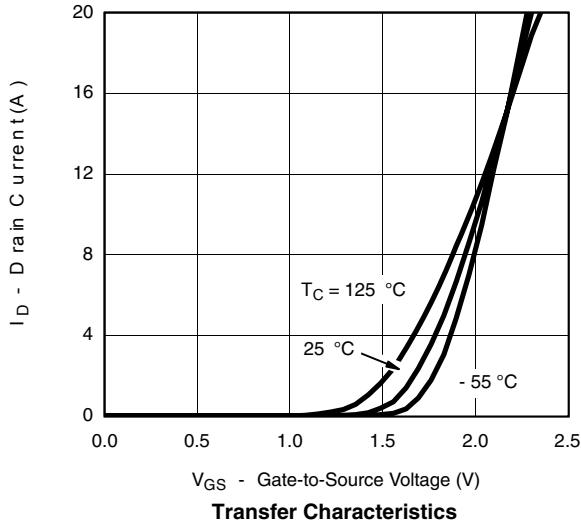
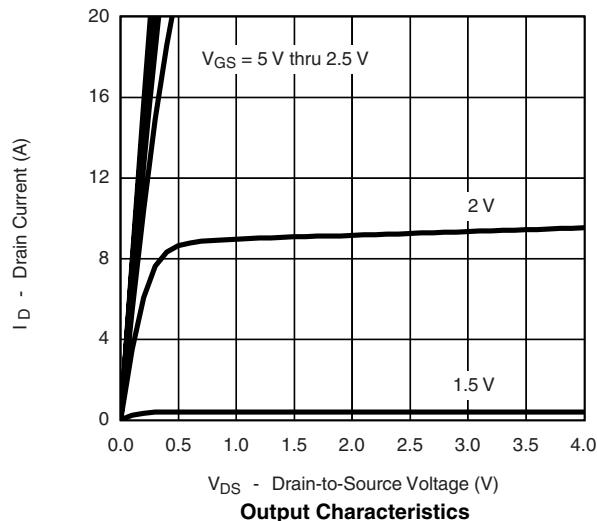
Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static						
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	N-Ch	0.6		1.5
		$V_{DS} = V_{GS}, I_D = -250 \mu\text{A}$	P-Ch	- 0.6		- 1.5
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$	N-Ch		± 100	nA
			P-Ch		± 100	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 12 \text{ V}, V_{GS} = 0 \text{ V}$	N-Ch		1	μA
		$V_{DS} = -12 \text{ V}, V_{GS} = 0 \text{ V}$	P-Ch		- 1	
		$V_{DS} = 12 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 55^\circ\text{C}$	N-Ch		5	
		$V_{DS} = -12 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 55^\circ\text{C}$	P-Ch		- 5	
On-State Drain Current ^a	$I_{D(\text{on})}$	$V_{DS} > 5 \text{ V}, V_{GS} = 4.5 \text{ V}$	N-Ch	20		A
		$V_{DS} \leq -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	P-Ch	- 20		
Drain-Source On-State Resistance ^a	$R_{DS(\text{on})}$	$V_{GS} = 4.5 \text{ V}, I_D = 11.8 \text{ A}$	N-Ch		0.014	Ω
		$V_{GS} = -4.5 \text{ V}, I_D = -8.9 \text{ A}$	P-Ch		0.026	
		$V_{GS} = 2.5 \text{ V}, I_D = 9.8 \text{ A}$	N-Ch		0.020	
		$V_{GS} = -2.5 \text{ V}, I_D = -6.9 \text{ A}$	P-Ch		0.043	
Forward Transconductance ^a	g_{fs}	$V_{DS} = 5 \text{ V}, I_D = 11.8 \text{ A}$	N-Ch		32	S
		$V_{DS} = -5 \text{ V}, I_D = -8.9 \text{ A}$	P-Ch		23	
Diode Forward Voltage ^a	V_{SD}	$I_S = 2.9 \text{ A}, V_{GS} = 0 \text{ V}$	N-Ch		0.77	V
		$I_S = -2.9 \text{ A}, V_{GS} = 0 \text{ V}$	P-Ch		- 0.8	
Dynamic^b						
Total Gate Charge	Q_g	N-Channel $V_{DS} = 6 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 11.8 \text{ A}$ P-Channel $V_{DS} = -6 \text{ V}, V_{GS} = -4.5 \text{ V}, I_D = -8.9 \text{ A}$	N-Ch		11.5	nC
Gate-Source Charge	Q_{gs}		P-Ch		13	
Gate-Drain Charge	Q_{gd}		N-Ch		3.2	
Gate-Drain Charge	Q_{gd}		P-Ch		4.1	
Gate Resistance	R_g		N-Ch	0.5	2.5	Ω
Turn-On Delay Time	$t_{d(\text{on})}$		P-Ch	1.5	3.5	
Rise Time	t_r	N-Channel $V_{DD} = 6 \text{ V}, R_L = 6 \Omega$ $I_D \cong 1 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 6 \Omega$ P-Channel $V_{DD} = -6 \text{ V}, R_L = 6 \Omega$ $I_D \cong -1 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 6 \Omega$	N-Ch		30	ns
Turn-Off Delay Time	$t_{d(\text{off})}$		P-Ch		35	
Fall Time	t_f		N-Ch		50	
Source-Drain Reverse Recovery Time	t_{rr}		P-Ch		42	
		$I_F = 2.9 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$	N-Ch		60	ns
		$I_F = -2.9 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$	P-Ch		54	
			N-Ch		25	ns
			P-Ch		17	
			N-Ch		40	ns
			P-Ch		40	
			N-Ch		80	
			P-Ch		80	

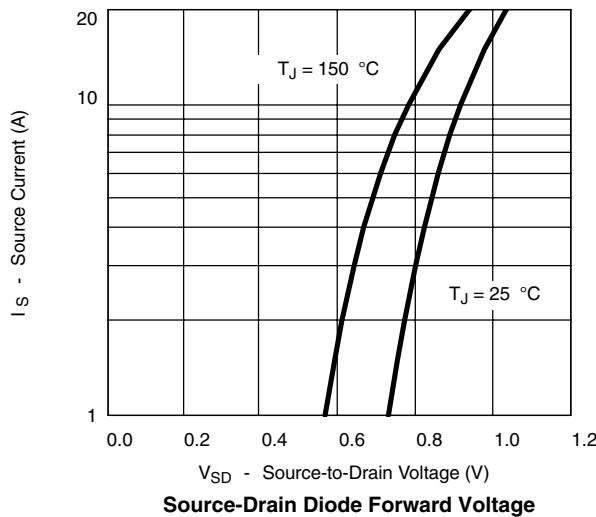
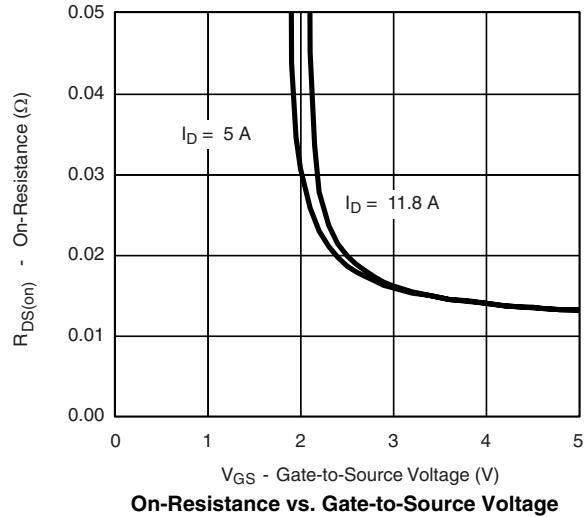
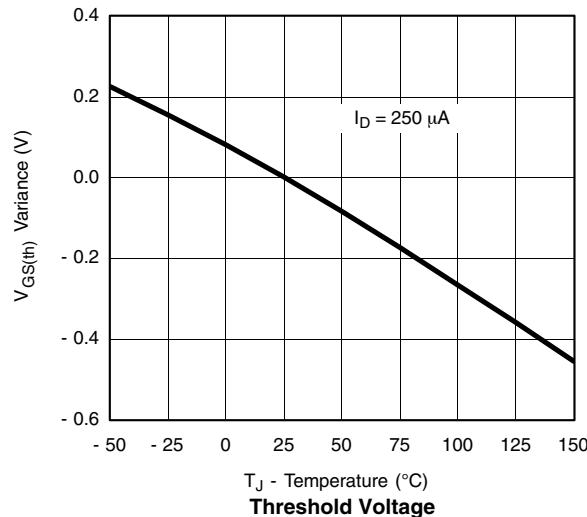
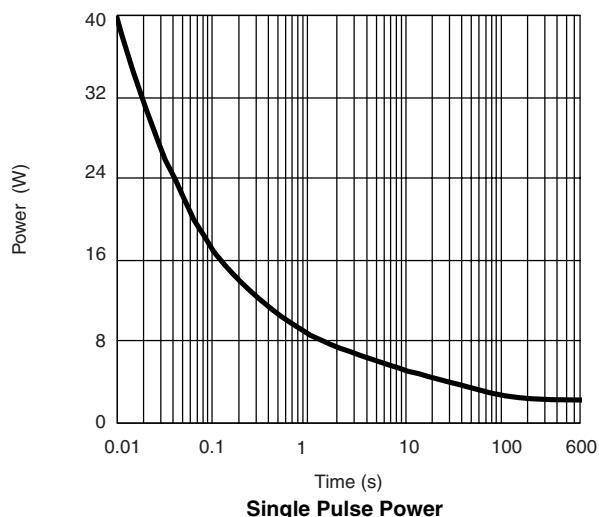
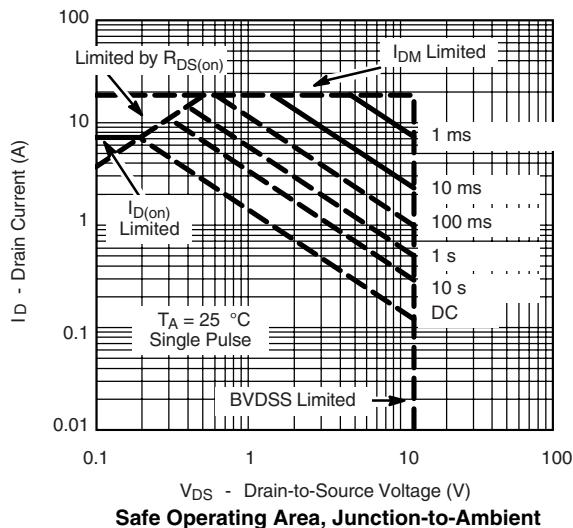
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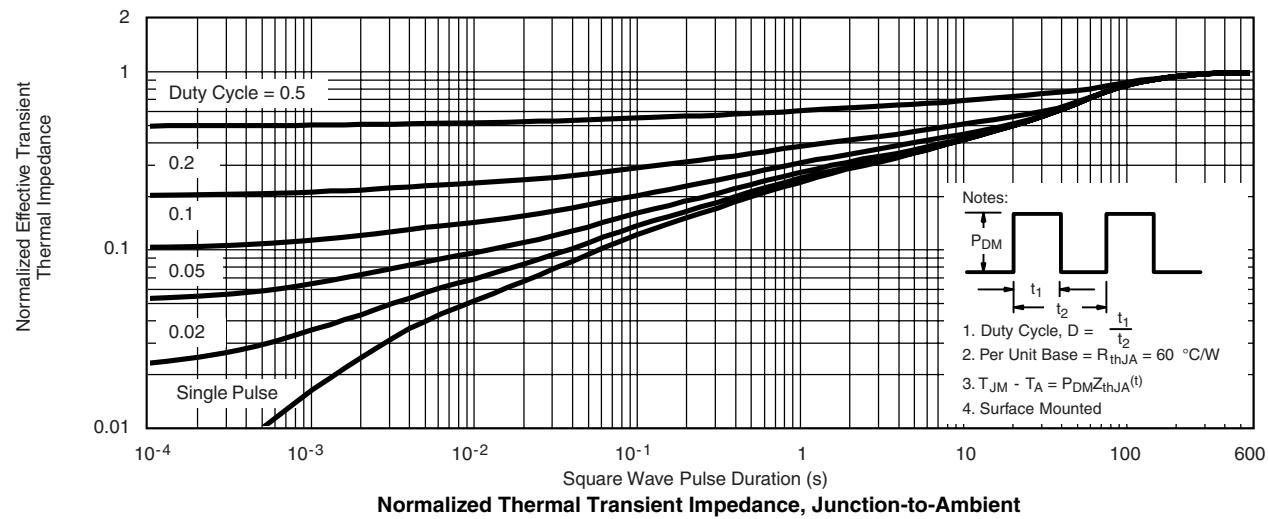
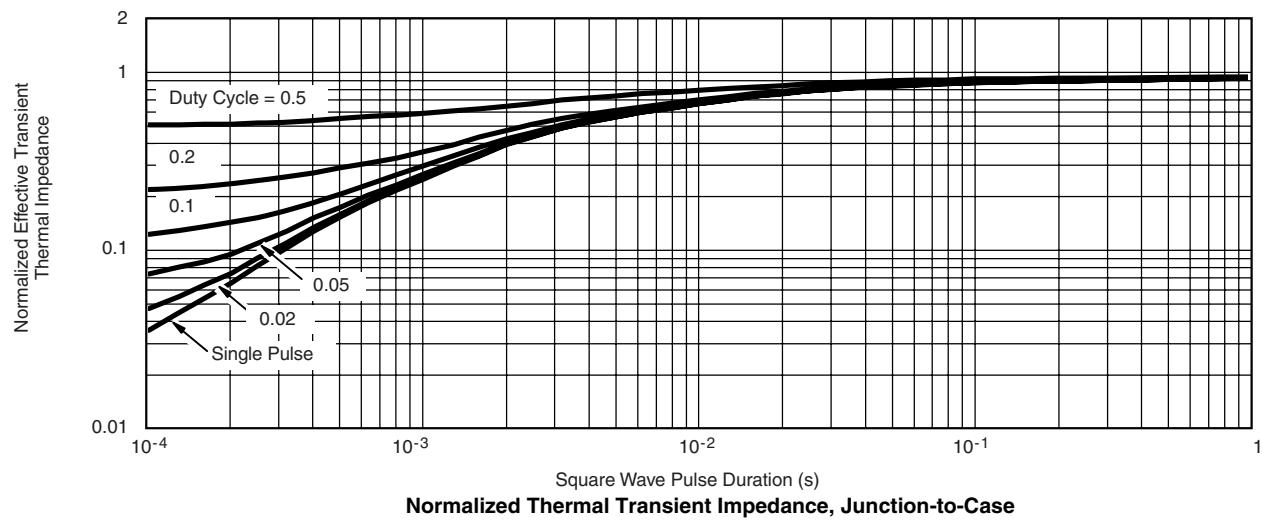
a. Pulse test; pulse width $\leq 300 \mu\text{s}$, duty cycle $\leq 2 \%$.

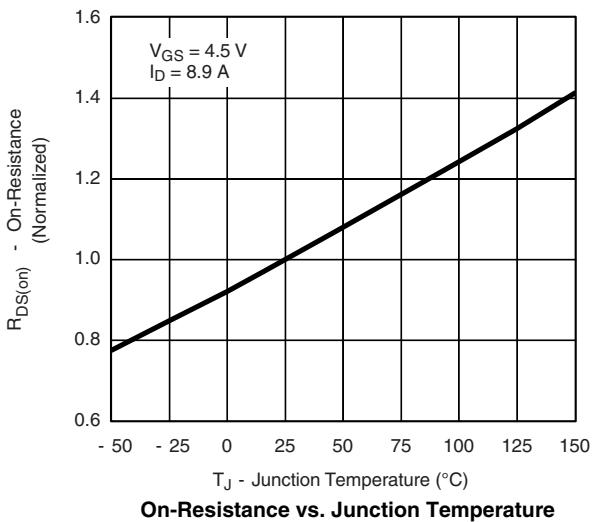
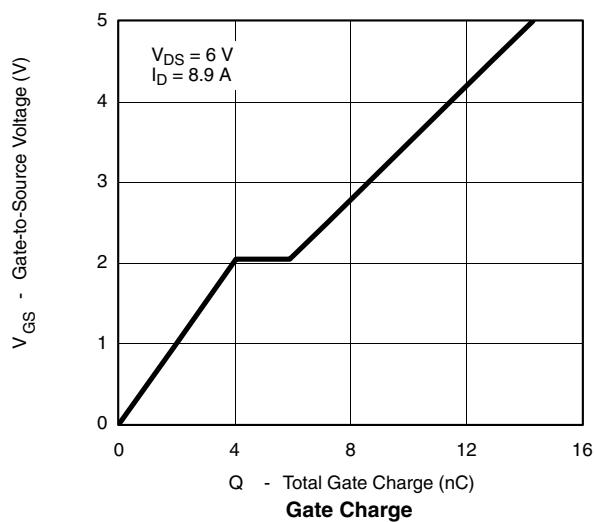
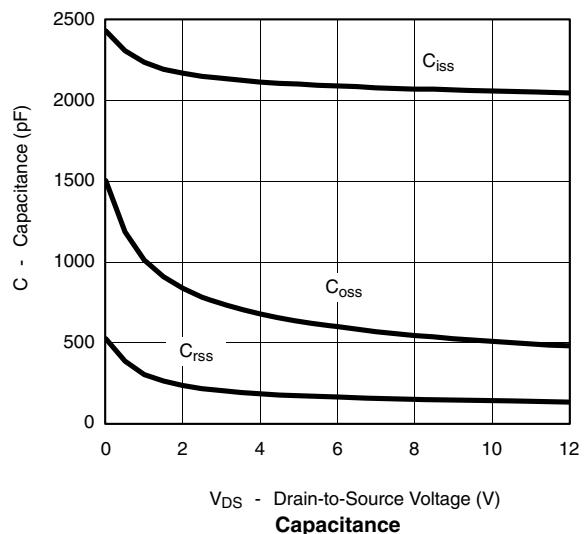
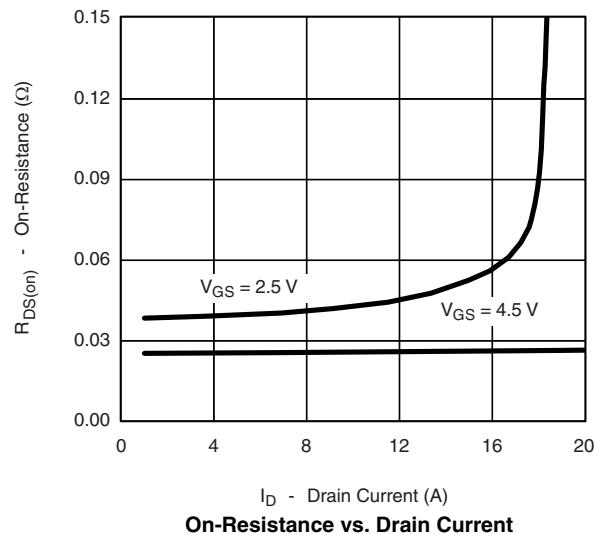
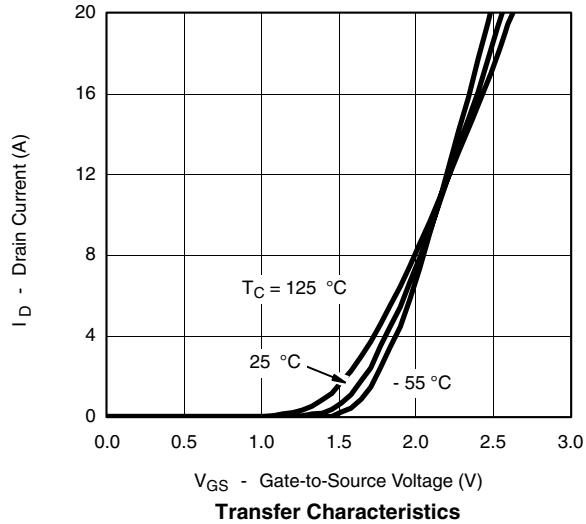
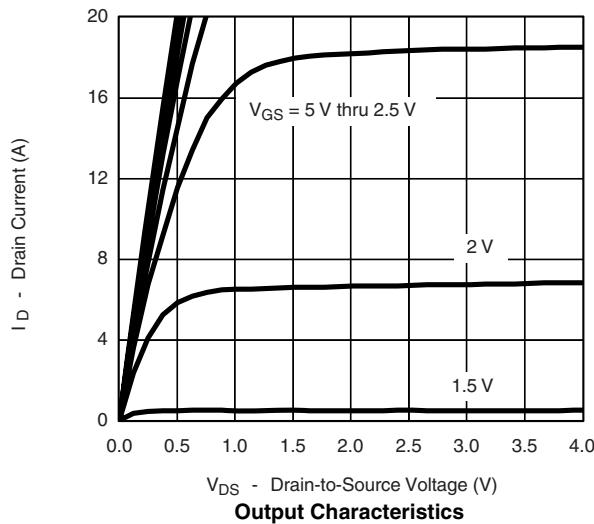
b. Guaranteed by design, not subject to production testing.

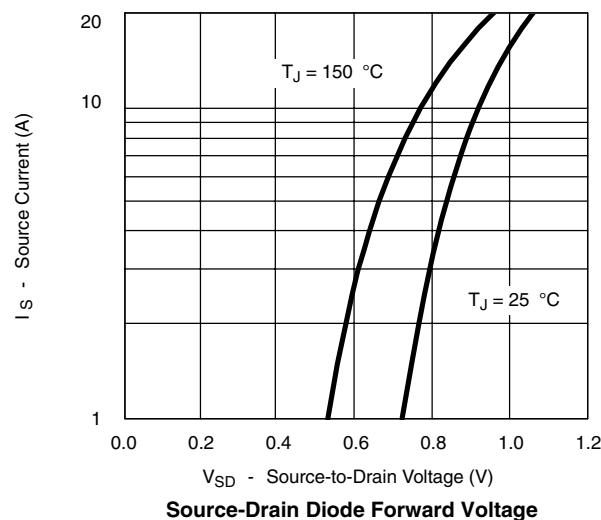
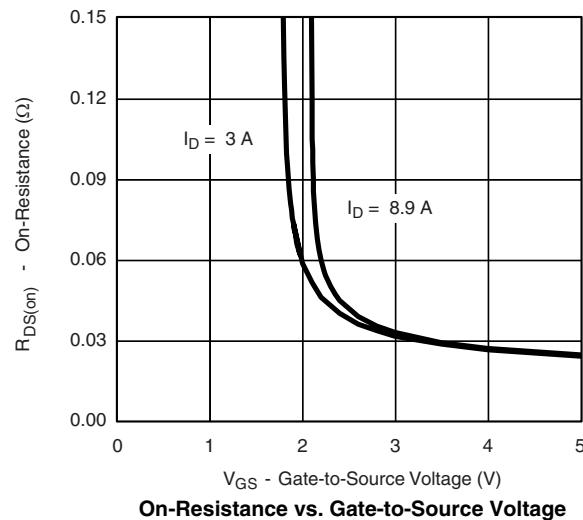
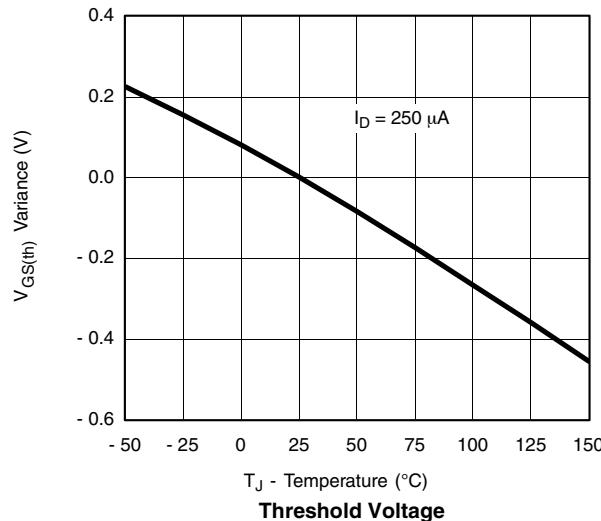
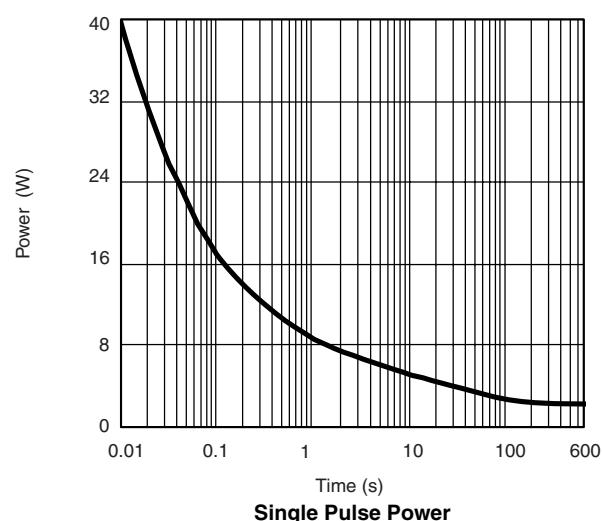
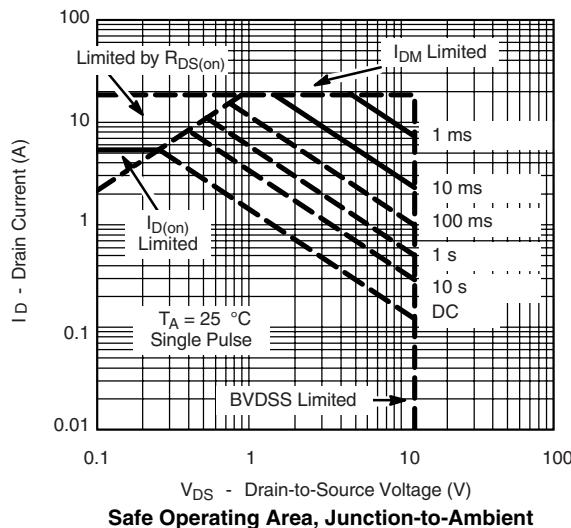
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

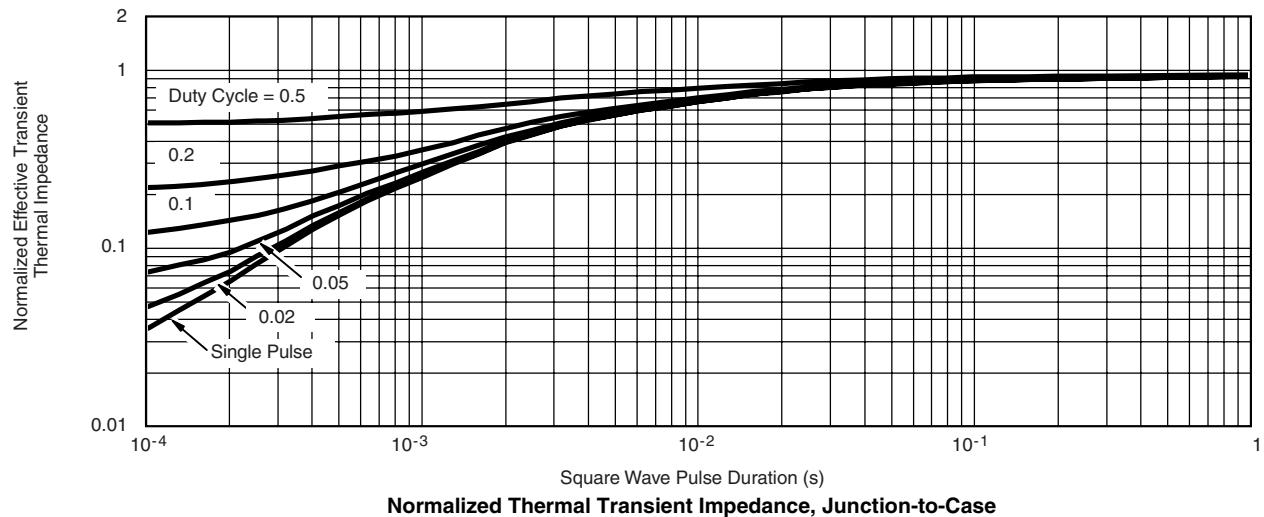
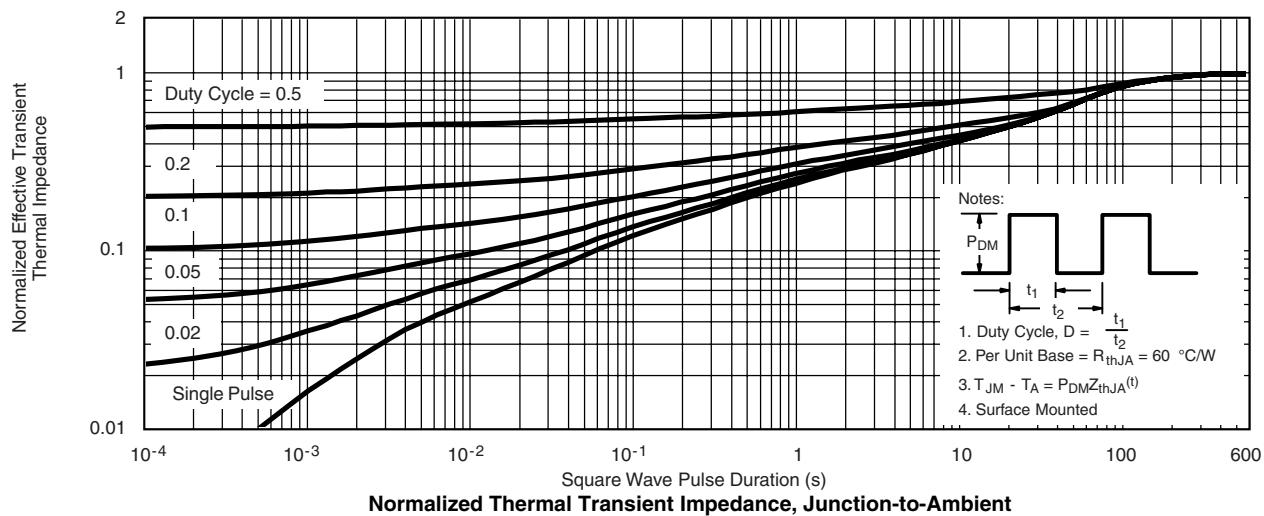
N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted


N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted**Source-Drain Diode Forward Voltage****On-Resistance vs. Gate-to-Source Voltage****Threshold Voltage****Single Pulse Power****Safe Operating Area, Junction-to-Ambient**

N-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

Normalized Thermal Transient Impedance, Junction-to-Ambient

Normalized Thermal Transient Impedance, Junction-to-Case

P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

Source-Drain Diode Forward Voltage

On-Resistance vs. Gate-to-Source Voltage

Threshold Voltage

Single Pulse Power


P-CHANNEL TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

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